

## WHAT IS CLAIMED IS:

1. A stacked semiconductor device comprising:

a plurality of semiconductor elements mounted on said device in a stacked form, each of said semiconductor elements having a quadrangular surface; and

a plurality of electrode pads provided on each of said quadrangular surfaces of said semiconductor elements, wherein

said electrode pads provided on each of said quadrangular surfaces are intensively arranged near two sides adjacent to each other, of said quadrangular surface, while

said semiconductor elements, which are adjacent to each other in a direction that said semiconductor elements are stacked, are arranged so as to be shifted in a direction parallel with said quadrangular surfaces in such a manner that said electrode pads provided on each of said semiconductor elements adjacent to each other do not overlap with the other semiconductor element when viewed from a direction orthogonal to said quadrangular surfaces.

2. A stacked semiconductor device comprising:

two semiconductor elements mounted on said device in a stacked form, each of said semiconductor elements having a quadrangular surface; and

a plurality of electrode pads provided on each of said

quadrangular surfaces of said semiconductor elements, wherein

5 said electrode pads provided on each of said quadrangular surfaces are intensively arranged near one side of said quadrangular surface, while

said semiconductor elements are arranged so as to be shifted in a direction parallel with said quadrangular surfaces in such a manner that said quadrangular surface of one of said semiconductor elements is faced to said quadrangular surface of the other semiconductor element and said electrode pads provided on each of said semiconductor elements do not overlap with the other semiconductor element when viewed from a direction orthogonal to said quadrangular surfaces.

15 3. A stacked semiconductor device comprising:

a plurality of semiconductor elements mounted on said device in a stacked form; and

a plurality of electrode pads provided on each of said semiconductor elements, wherein

20 said electrode pads provided on each of said semiconductor element are arranged on a side surface of said semiconductor element.

4. The stacked semiconductor device according to claim 3, wherein each of said side surfaces is slanted for a horizontal surface of said semiconductor element.

5. The stacked semiconductor device according to claim 1, wherein

said semiconductor elements, which are adjacent to each other in the direction that said semiconductor elements are stacked, are directly joined to each other by means of an adhesive.

6. The stacked semiconductor device according to claim 2, wherein

said semiconductor elements are directly joined to each other by means of an adhesive.

7. The stacked semiconductor device according to claim 3, wherein

said semiconductor elements, which are adjacent to each other in the direction that said semiconductor elements are stacked, are directly joined to each other by means of an adhesive.

8. The stacked semiconductor device according to claim 4, wherein

said semiconductor elements, which are adjacent to each other in the direction that said semiconductor elements are stacked, are directly joined to each other by means of an adhesive.